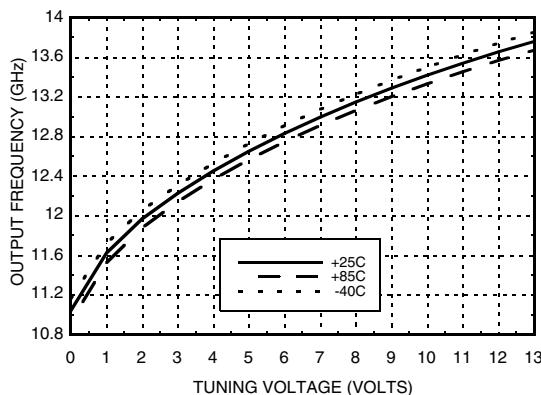
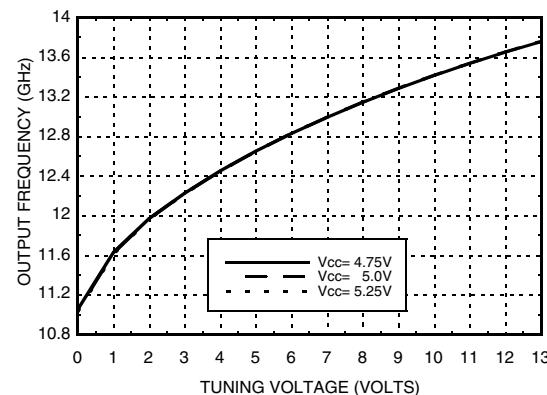
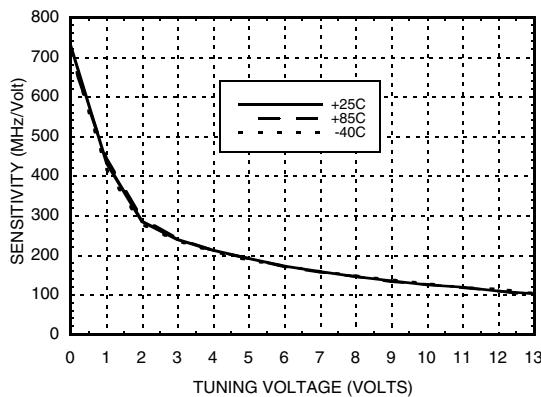
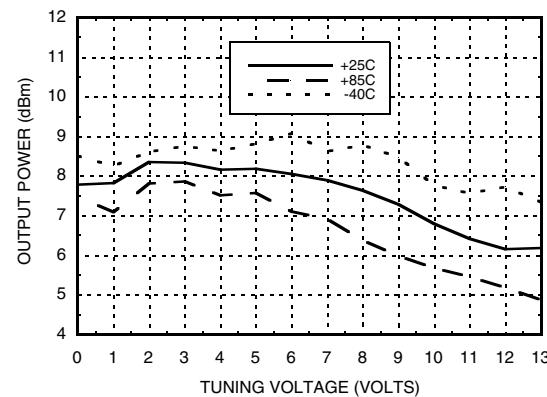
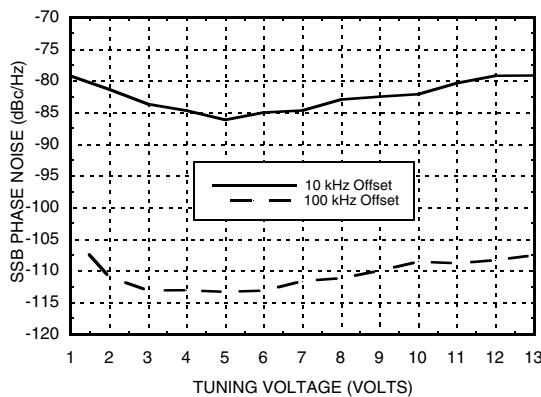
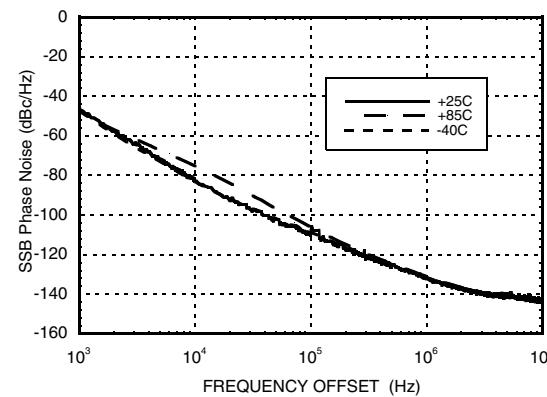
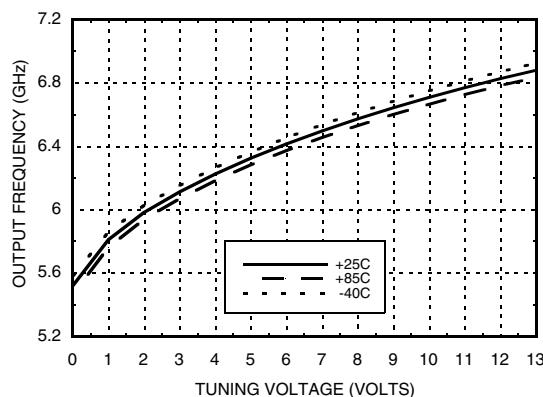
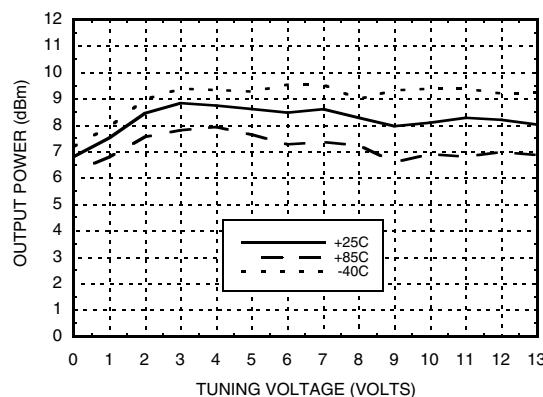
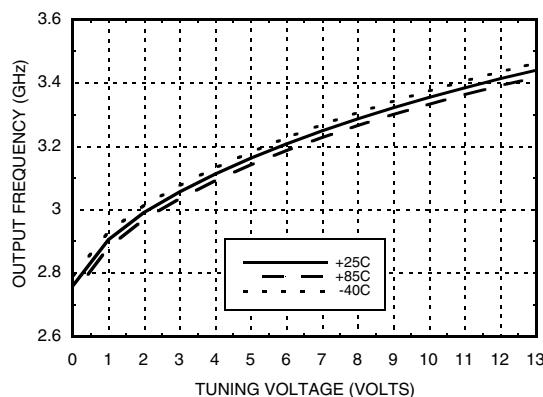
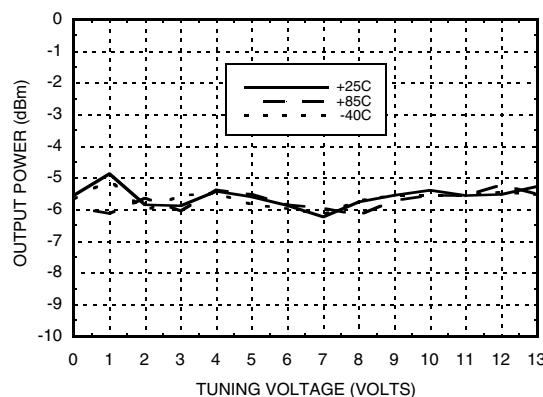



**MMIC VCO w/ HALF FREQUENCY OUTPUT
& DIVIDE-BY-4, 12.4 - 13.4 GHz**
Frequency vs. Tuning Voltage, $V_{cc} = +5V$

Frequency vs. Tuning Voltage, $T = 25^{\circ}C$

Sensitivity vs. Tuning Voltage, $V_{cc} = +5V$

**Output Power
vs. Tuning Voltage, $V_{cc} = +5V$**

SSB Phase Noise vs. Tuning Voltage

SSB Phase Noise @ $V_{tune} = +5V$


Information furnished by Analog Devices is believed to be accurate and reliable. However, no responsibility is assumed by Analog Devices for its use, nor for any infringements of patents or other rights of third parties that may result from its use. Specifications subject to change without notice. No license is granted by implication or otherwise under any patent or patent rights of Analog Devices. Trademarks and registered trademarks are the property of their respective owners.

For price, delivery, and to place orders: Analog Devices, Inc., One Technology Way, P.O. Box 9106, Norwood, MA 02062-9106 Phone: 781-329-4700 • Order online at www.analog.com Application Support: Phone: 1-800-ANALOG-D


**RFOUT/2 Frequency
vs. Tuning Voltage, Vcc= +5V**

**RFOUT/2 Output Power
vs. Tuning Voltage, Vcc= +5V**

**Divide-by-4 Frequency
vs. Tuning Voltage, Vcc= +5V**

**Divide-by-4 Output Power
vs. Tuning Voltage, Vcc= +5V**

Absolute Maximum Ratings

Vcc1, Vcc2	+5.5 Vdc
Vtune	0 to +15V
Junction Temperature	135 °C
Continuous Pdiss (T=85 °C) (derate 37 mW/C above 85 °C)	1.85 W
Thermal Resistance (junction to ground paddle)	27 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
ESD Sensitivity (HBM)	Class 1A

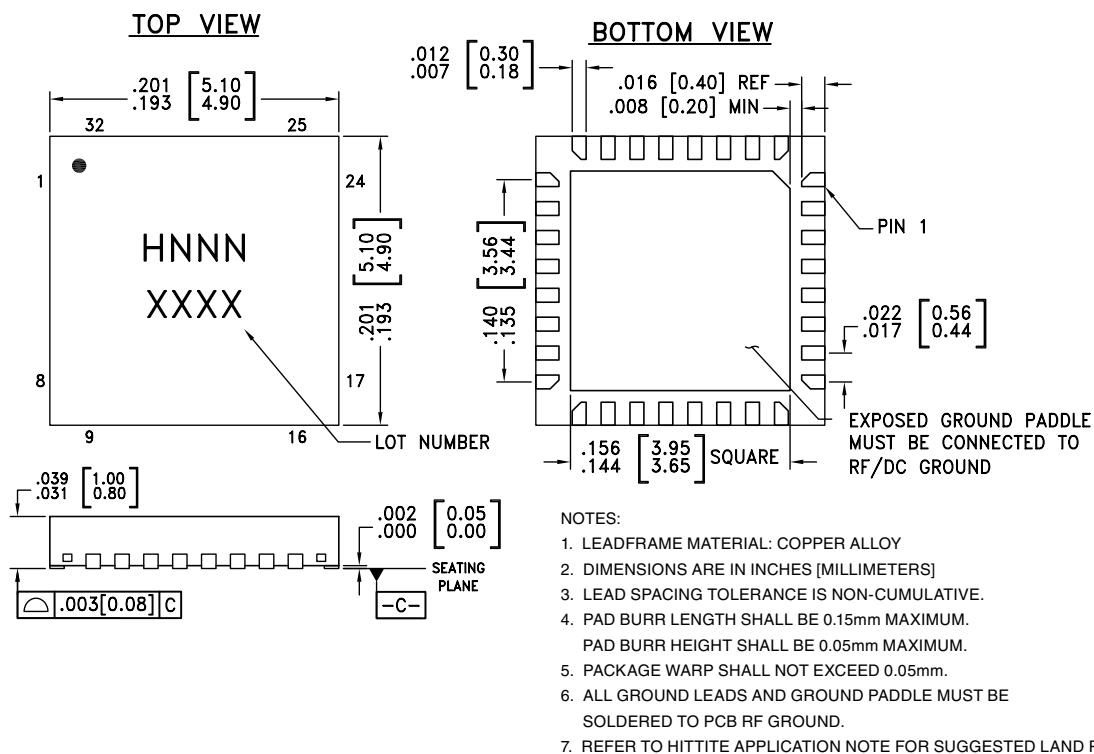
Typical Supply Current vs. Vcc

Vcc (V)	Icc (mA)
4.75	235
5.00	260
5.25	275

Note: VCO will operate over full voltage range shown above.



ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS


**MMIC VCO w/ HALF FREQUENCY OUTPUT
& DIVIDE-BY-4, 12.4 - 13.4 GHz**
Outline Drawing

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking ^[3]
HMC529LP5	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL3 ^[1]	H529 XXXX
HMC529LP5E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL3 ^[2]	H529 XXXX

[1] Max peak reflow temperature of 235 °C

[2] Max peak reflow temperature of 260 °C

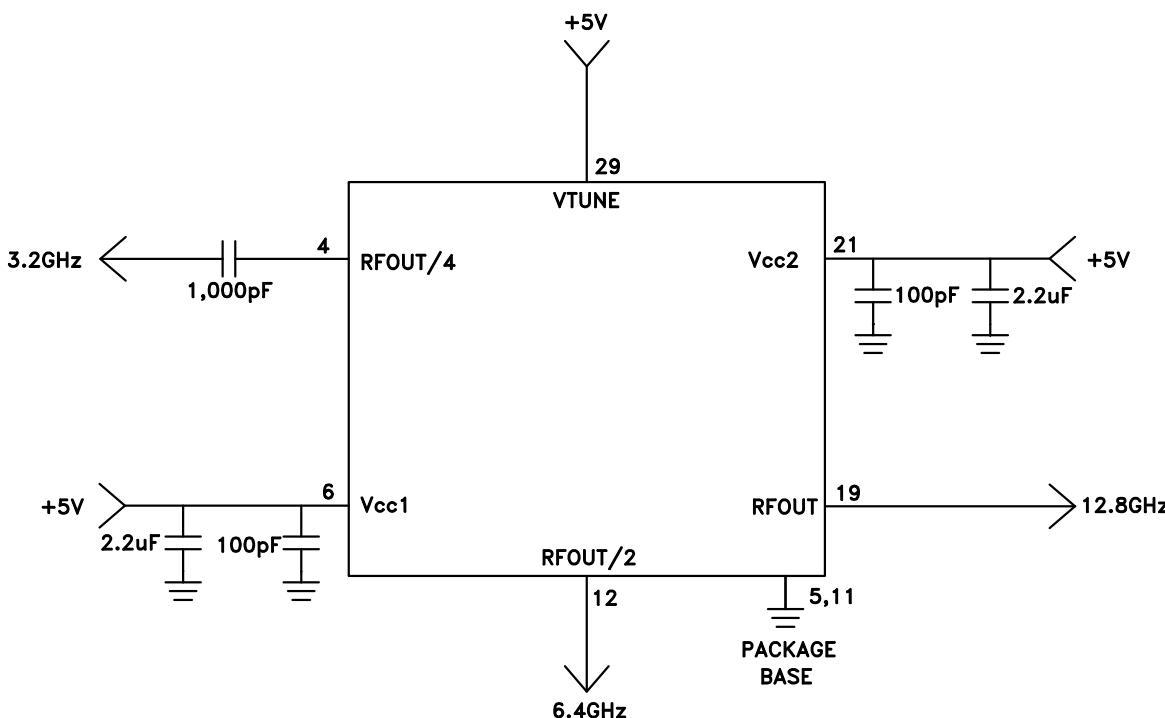
[3] 4-Digit lot number XXXX

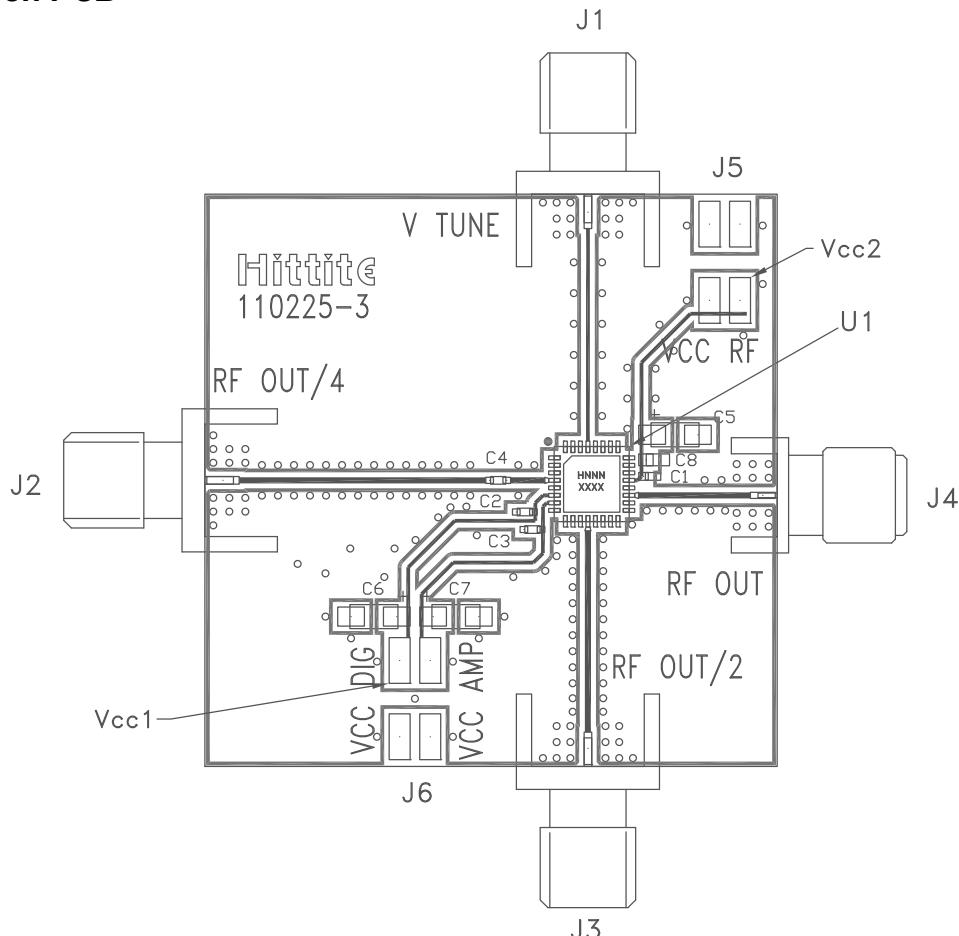
Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1 - 3, 7 - 10, 13 - 18, 20, 22 - 28, 30 - 32	N/C	No Connection. These pins may be connected to RF/DC ground. Performance will not be affected.	
4	RFOUT/4	Divide-by-4 Output.	
6	Vcc1	Supply Voltage for prescaler. If prescaler is not required, this pin may be left open to conserve 65 mA of current.	


**MMIC VCO w/ HALF FREQUENCY OUTPUT
& DIVIDE-BY-4, 12.4 - 13.4 GHz**
Pin Descriptions

Pin Number	Function	Description	Interface Schematic
12	RFOUT/2	Half frequency output (AC coupled).	
19	RF OUT	RF output (AC coupled).	
21	Vcc2	Supply Voltage, +5V	
29	VTUNE	Control Voltage and Modulation Input. Modulation bandwidth dependent on drive source impedance. See "Determining the FM Bandwidth of a Wideband Varactor Tuned VCO" application note.	
5, 11, Paddle	GND	Package bottom has an exposed metal paddle that must be connected to RF/DC ground.	

Typical Application Circuit



**MMIC VCO w/ HALF FREQUENCY OUTPUT
& DIVIDE-BY-4, 12.4 - 13.4 GHz**
Evaluation PCB

List of Materials for Evaluation PCB 110227^[1]

Item	Description
J1 - J4	PCB Mount SMA RF Connector
J5 - J6	2 mm DC Header
C1 - C3	100 pF Capacitor, 0402 Pkg.
C4	1,000 pF Capacitor, 0402 Pkg.
C5 - C7	2.2 μ F Tantalum Capacitor
U1	HMC529LP5(E) VCO
PCB ^[2]	110225 Eval Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Arlon 25FR

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and backside ground paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.